R263-Z37-AAH1

Rack Server - 2U UP 12+2-Bay NVMe/SATA







Key Features

- Single AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 12 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 8 x 3.5"/2.5" SATA/SAS-4 hot-swap bays
- 2 x 2.5" Gen5 NVMe hot-swap bays on the rear side
- 1 x M.2 slot with PCle Gen3 x4 interface
- 4 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCle Gen5 x16 slots
- 2 x 1300W 80 PLUS Titanium redundant power supply

Application

Networking, Hybrid/Private Cloud Server...

Specification

Dimensions	2U (W438 x H87.5 x D710 mm)	I/O Po
Motherboard	MZ33-DC1	D I
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Single processor, cTDP up to 400W	Backp Secur
	 - At 25°C ambient, cTDP up to 500W - At 30°C ambient, cTDP up to 500W with optional heatsink 	Power
Sock	1 x LGA 6096 (Socket SP5)	rowei
Chipset	System on Chip	Syste
Memory	12-Channel DDR5 RDIMM, 12 x DIMMs [EPYC 9005] Up to 6000 MT/s [EPYC 9004] Up to 4800 MT/s	OS Su
LAN	1 x 1Gb/s LAN (1 x Intel® I210-AT) - Supports NCSI function	Syste
	1 x 10/100/1000 Mbps Management LAN	Opera Prope
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP	
Storage	Front hot-swap: 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 8 x 3.5"/2.5" SATA/SAS-4 *SAS card is required to support SAS drives. Rear hot-swap: 2 x 2.5" Gen5 NVMe	Packa Conte
	Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x4	Part N
RAID	Require RAID add-in cards	
Expansion Slots	4 x FHHL PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots - Supports NCSI function	

orts Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN

plane Board Front - CBP20C7: PCle Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s Rear - CBP2025: PCIe Gen5 x4

rity Modules 1 x TPM header with SPI interface

- Optional TPM2.0 kit: CTM012

2 x 1300W 80 PLUS Titanium redundant power supply er Supply

AC Input: 100-240V

ASPEED® AST2600 Baseboard Management Controller gement

GIGABYTE Management Console web interface

Windows Server, Red Hat Enterprise Linux server, Ubuntu, upport SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor

em Fans 4 x 80x80x38mm (18,300rpm)

ating Operating temperature: 10°C to 30°C erties Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C

Non-operating humidity: 20%-95% (non-condensing)

aging 1 x R263-Z37-AAH1, 1 x CPU heatsink,

ent 1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit

Packaging Dimensions: 989 x 594 x 279 mm

Barebone package: 6NR263Z37DR000ACH1* Numbers

Optional parts:

- 3-Section Rail kit (Supports CMA): 25HB2-A56121-K0R

- Cable Management Arm: 25HB1-R18300-K0R

- CPU heatsink (500W, 30°C ambient): 25ST1-563400-C1R



Learn more at https://www.GIGABYTE.com/enterprise

* All specifications are subject to change without notice. Please visit our website for the latest information.

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